belkin

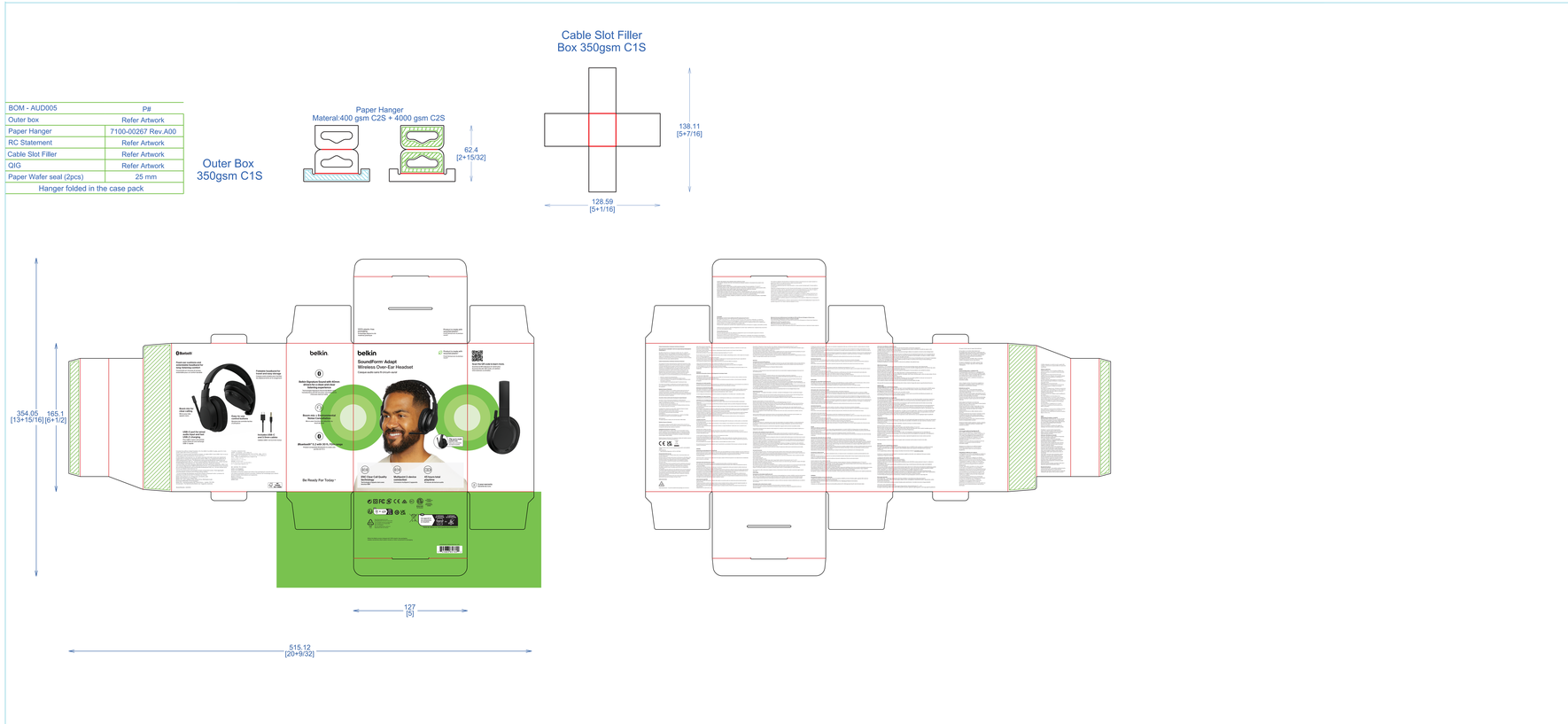
Die Line File: IDL_AUD005_PROEJECT OVER EAR HEADPHONES

Artwork File:

REV 0 01

## DIE LAYOUT

| BOM - AUD005 | P# |
|---|---|
| Outer box | Refer Artwork |
| Paper Hanger | 7100-00267 Rev.A00 |
| RC Statement | Refer Artwork |
| Cable Slot Filler | Refer Artwork |
| QIG | Refer Artwork |
| Paper Wafer seal (2pcs) | 25 mm |
| Hanger folded in the case pack | |




Business Unit: Core

Program Manager: Andrew Camba

Packaging Engineer: Matthew Duffy

Retail Outside Dimension (Including Hang Tab)

L x W x D (in):

L x W x D (mm):

DIE/MATERIAL SPECS:

Material: Please refer to drawing

Blank Size (in): 64.053 x 23.725

Blank Size (mm): 1626.935 x 602.615

This dieline works for following skus (if any):

Unit: IN/MM

Side Shown: PRINT SIDE

Flute/Grain: horizontal

Tolerance:+/- 1/32" - 0.8mm

Drawing Scale 1:1

RELEASE DATE: 05/18/2023

DIELINE:

Intermediate

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PRINT SPECS:

Color Plates:

Finish:

Notes:

DO NOT PRINT
DIE LINES, PRINTERS NOTES